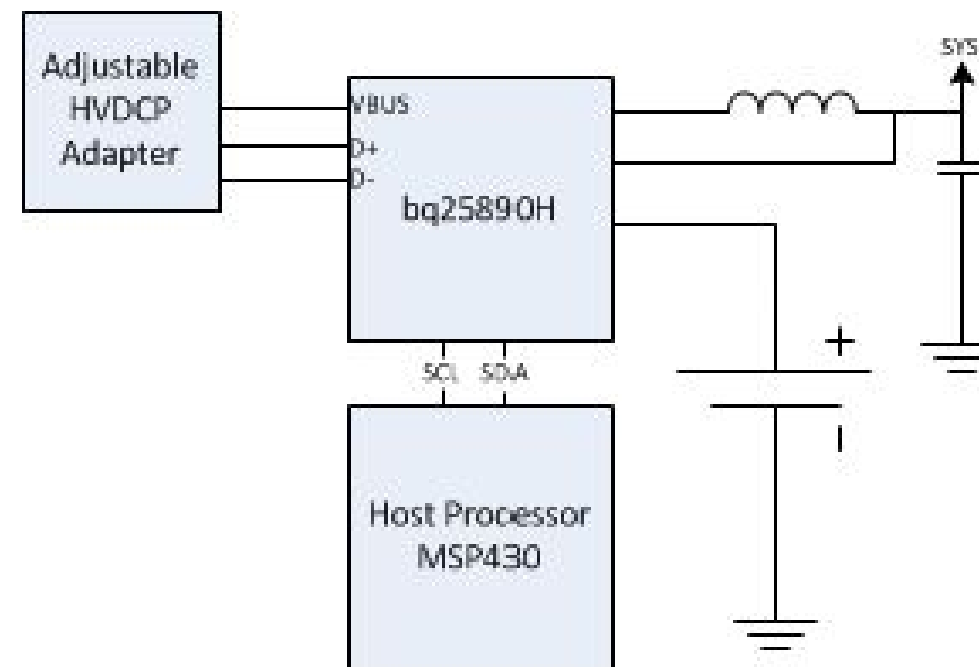



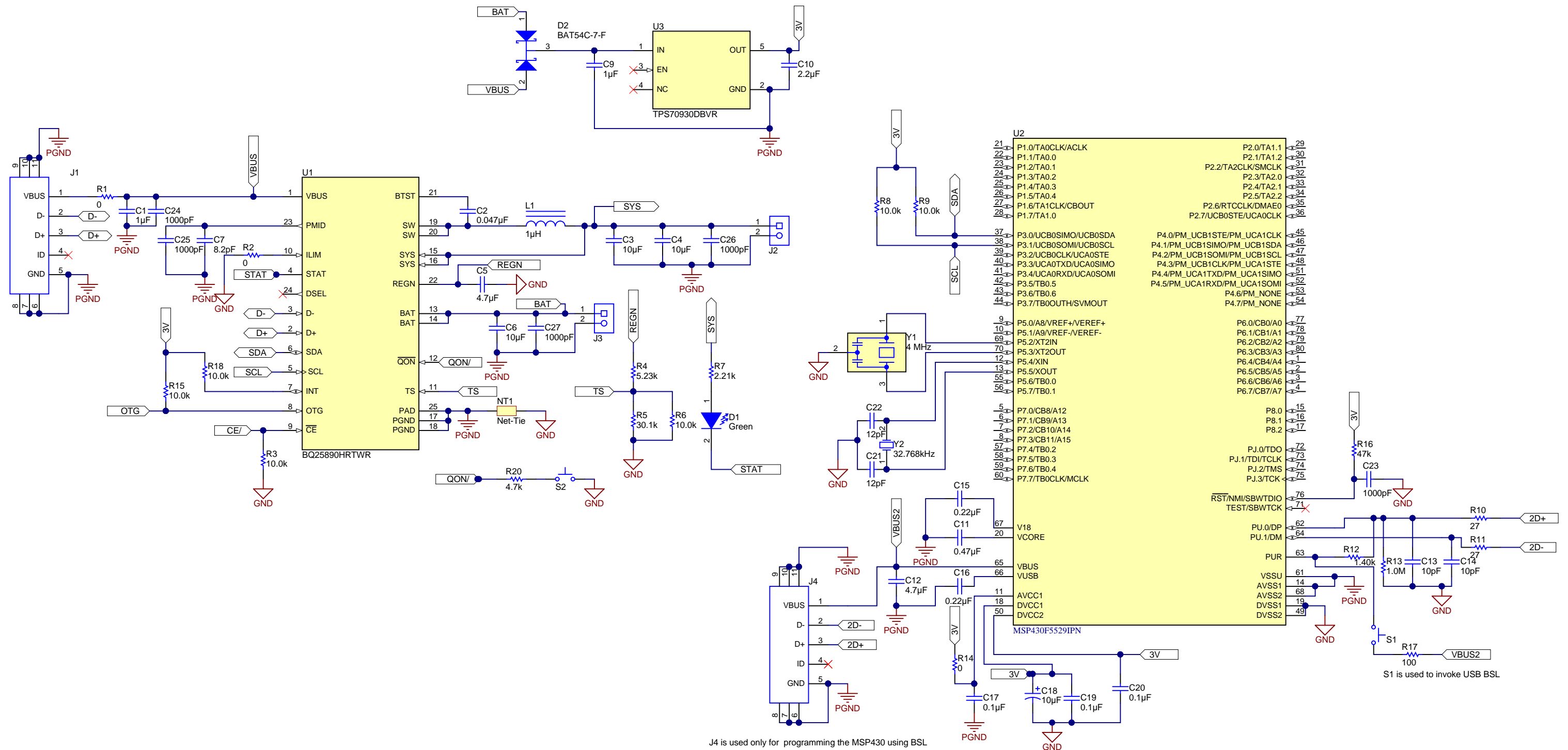
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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TID #: TIDA-03029	Project Title: MaxCharge HVDCP Handshaking		
Number: TIDA-03029	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By:	File: CoverSheet.SchDoc	Size: B	
Engineer: Fernando Lopez	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



J4 is used only for programming the MSP430 using BSL

S1 is used to invoke USB BSL

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